TOSHIBA 2SK2843

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

2 S K 2 8 4 3

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATORS, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.54 \Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fs}| = 9.0 \,\mathrm{S}$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 600 \,\text{V}$)

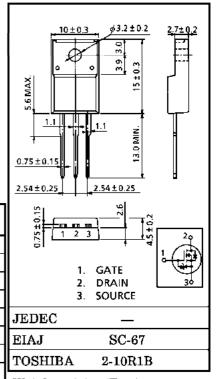
: $V_{th} = 2.0 \sim 4.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERI	SYMBOL	RATING	UNIT			
Drain-Source Voltage	$v_{ m DSS}$	600	V			
Drain-Gate Voltage (Ro	VDGR	600	V			
Gate-Source Voltage	v_{GSS}	±30	V			
Drain Current	DC	$I_{\mathbf{D}}$	10	Α		
	Pulse	I_{DP}	40	Α		
Drain Power Dissipation	$P_{\mathbf{D}}$	45	W			
Single Pulse Avalanche	E_{AS}	363	mJ			
Avalanche Current	I_{AR}	10	Α			
Repetitive Avalanche E	$\mathbf{E}_{\mathbf{A}\mathbf{R}}$	5.0	mJ			
Channel Temperature	$\mathrm{T_{ch}}$	150	$^{\circ}\mathrm{C}$			
Storage Temperature R	$\mathrm{T_{stg}}$	-55~150	$^{\circ}\mathrm{C}$			

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 1.9 g (Typ.)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	Rth (ch-c)	2,78	°C/W
Thermal Resistance, Channel to Ambient	Rth (ch-a)	62.5	°C/W

Note;

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** V_{DD} = 90 V, Starting T_{ch} = 25°C, L = 6.36 mH, R_{G} = 25 Ω , I_{AR} = 10 A

This transistor is an electrostatic sensitive device. Please handle with caution.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARAC	TERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	$_{\mathrm{IGSS}}$	$V_{GS} = \pm 25 V, V_{DS} = 0 V$	-	_	±10	μ A
Gate-Source B Voltage	reakdown	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	v
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μ A
Drain-Source I Voltage	Breakdown	V (BR) DSS	$I_{\mathrm{D}}=10\ \mathrm{mA},\ \mathrm{V}_{\mathrm{GS}}=0\ \mathrm{V}$	600	_	_	v
Gate Threshol	d Voltage	$ m v_{th}$	$V_{DS} = 10 V, I_{D} = 1 mA$	2.0		4.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	_	0.54	0.75	Ω
Forward Trans Admittance	sfer	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	3.0	9.0	_	s
Input Capacitance		$\mathrm{C}_{\mathrm{iss}}$		_	2040	_	
Reverse Transfer Capacitance		Crss	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	_	230	_	рF
Output Capaci	tance	Coss		_	590	_	
Turn Switching Time Fall	Rise Time	t _r	$V_{GS} \stackrel{10}{_{0}} V \stackrel{I_{D} = 5 \text{ A}}{\underset{\sim}{\text{NOUT}}} V_{OUT}$	_	22	_	
	Turn-on Time	t _{on}		_	58	_	ns
	Fall Time	t_f		I	36	_	113
	Turn-off Time	t _{off}	$V_{ extbf{IN}}: extbf{t}_{ extbf{r}}, extbf{t}_{ extbf{f}} < 5 ext{ ns,} \ V_{ extbf{DD}} = 200 ext{ V} \ ext{Duty} \le 1\%, extbf{t}_{ extbf{W}} = 10 ext{ } \mu ext{s}$	_	190	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		Q_g	$V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V},$	_	45	_	C
Gate-Source Charge		Q_{gs}	$I_D = 10A$	_	25	_	nC
Gate-Drain ("Miller") Charge		Q_{gd}		_	20	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_		_	10	A
Pulse Drain Reverse Current	IDRP	_	_	_	40	A
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse Recovery Time	t _{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$		1300	_	ns
Reverse Recovery Charge	$Q_{ m rr}$	$dI_{DR}/dt = 100 A/\mu s$		16	_	μC

MARKING

